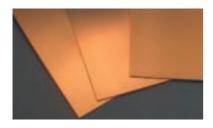


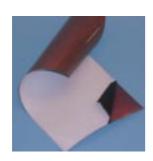
- Blue colored positive resin, without marbles
- Micro definition, resin thickness 2.5 µ.
- Adhesive anti UV-protection
- 5 years shelf life garanty.
- Individual packaging in plastic bag up to size 200 x 300 mm.

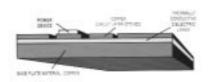


Special cut out price per m2 upon request For FR 4 in 2/10th - 35μ please consult CIF



Special cut out price per m2 upon request For FR 4 in 4/10th and 2/10th please consult CIF





PRE-SENSITISED PHOTOPOSITIVE BOARDS

PRE-SENSITISED P							
Positive Epoxy FR4 Positive Bakelite	16/10 th - 35 μ	Size in mm	Bakelite 15/10th I side	Epoxy I side	Epoxy 2 sides		
i obieive Baiteilee	15/10 - 35 μ	75 x 100	AC 7	Reference AA 7	AB 7		
		100 x 150	AC 10	AA 10	AB IO		
		100 x 160	AC 16	AA 16	AB 16		
		150 x 200	AC 15	AA 15	AB 15		
		200 x 300	AC 20	AA 20	AB 20		
		300 x 600	AC 60	AA 60	AB 60		
		600 x 900	AC 90	AA 90	AB 90		
Positive Epoxy FR4	8/10 th - 35 μ	- 33 µ	Ероху	Ероху			
Tositive Epoxy I N4	0/10 - 35 μ		mm		2 sides		
				Reference			
		100	0 x 160	AAB 16	ABB 16		
		200	0 x 300	AAB 20	ABB 20		
			0 x 600	AAB 60	ABB 60		
		600	0 x 900	AAB 90	AAB 90		
Davidina Francis FD4	4/10th 2F	s	ize in	Ероху	Ероху		
Positive Epoxy FR4	4/10 th - 35 μ		mm	l side	2 sides		
					Reference		
		100	0 x 160	AAC 16	ABC 16		
			0 x 300	AAC 20	ABC 20		
			0 x 600	AAC 60	ABC 60		
		600	0 x 900	AAC 90	ABC 90		
		s	ize in	Ероху	Ероху		
Positive Epoxy FR4	16/10 th - 70 μ		mm	I side	2 sides		
				Refer	ence		
		100	0 x 160	AA 716	AB 716		
		200	0 x 300	AA 720	AB 720		
		300	0 x 600	AA 760	AB 760		
		600	0 x 900	AA 790	AB 790		
T. G (D)	16/10 th - 35 μ		iize in	2 si	des		
Teflon (Duroïd) High frequency sensitised, double sided.		-	mm		Reference		
		100 x 160		ABT 16			
Di-electric constant 2,4 - 2,6 (±	0,04).	20	0 x 300	ABT 23			
		40	6 x 915	AB	Г 47		
Teffer (Dureïd)	8/10 th - 35 μ	•	iize in	7 ci	des		
Teflon (Duroïd)	•		mm		rence		
High frequency sensitised, double	20	0 x 300	ABT 18				
Di-electric constant 2,4 - 2,6 (±	300 x 600 ABT 186						

UNCOATED PCB LAMINATES

Epoxy FR4							
Bakelite							
High quality laminate with	8	lavers					

High quality laminate with 8 layers of fibre glass. Standard MIL 13949 for the FR4 UL94 Vo. Individual packaging in plastic bag upto size 200x300

/10 th - 35 μ	Size in mm	Bakelite 15/10th I side	Epoxy I side	Epoxy 2 sides
/10 th - 35 μ		Reference		
/10 - 33 μ	75 x 100	AF 7	AD 7	AE 7
	100 x 150	AF 10	AD 10	AE I0
	100 x 160	AF 16	AD 16	AE 16
	150 x 200	AF 15	AD 15	AE 15
	200 x 300	AF 20	AD 20	AE 20
	300 x 300	AF 30	AD 30	AE 30
	300 x 600	AF 60	AD 60	AE 60
	600 x 900	AF 90	AD 90	AE 90

200 x 600

Size in

100 x 150

200 x 300

300 x 600

620 x 920

Epoxy FR4

Special cut out price per m2 upon request For FR 4 in 4/10th and 2/10th please consult CIF

Flexible Circuits							
Bare Insulation 50 μ - copper cladding	35 _l	-					

Presensitised photopositive Insulation 50 μ - copper cladding 35 μ .

Size in	Epoxy Epoxy
mm	I side 2 sides
	Reference
100 x 160	ADB 16 AEB 16
200 x 300	ADB 20 AEB 20
300 x 600	ADB 60 AEB 60
600 x 900	ADB 90 AEB 90
Size in	I side 2 sides
mm	Reference
100 x 600	AN 10 AN 210
200 x 600	AN 20 AN 220
600 x 900	AN 60 AN 260
Size in	I side
mm	Reference
100 x 600	AQ 10

ALUMINIUM PHOTOPOSITIVE CIRCUITS

<u>8/10</u>th - 35 μ

- Heat dissipation > I °C / Watt / mm2
- Adhesion to copper > 22N/cm
- Working Temperature 130 °C continuous
- Electrical strength (for 100µ) 51 KV/mm
- Di-electric constant = 3 at IMHz Dissipation power 0,35 Watt /dm2 / °C



AQ 20

Reference

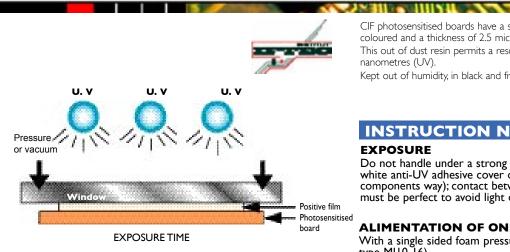
AAT 10

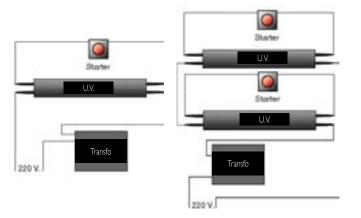
AAT 20

AAT 30

AAT 61

Positive presensitised boards, general information





CIF photosensitised boards have a strong and very adhesive cover, blue-purple coloured and a thickness of 2.5 microns.

This out of dust resin permits a resolution of about 2 microns. Sensitivity to light: 365 nanometres (UV).

Kept out of humidity, in black and fresh area, CIF boards are 5 years guaranteed.

INSTRUCTION NOTICE

EXPOSURE

Do not handle under a strong light or near a shiny window. Take the white anti-UV adhesive cover off. Install the mylar (locating copper or components way); contact between photosensitised layer and board must be perfect to avoid light diffraction through the mylar thickness.

ALIMENTATION OF ONE OR TWO UV-TUBES

With a single sided foam pressure machine: 2 to 2.30 min (CIF machine type MII0-I6)

With a vacuum machine: 90sec to 2 min (CIF machine type DFT3040). In case of vegetal copy use, time has to be increased from 20 to 30% depending on the thickness of the copy.

Nota: in any case, with a good film quality, it is better you overinsulate than underinsulate.

DEVELOPMENT

In a tray containing I litre of CIF developer (bag to be diluated or ready to use solution), put the circuit and shake at 20°C. Development must take between 30

Insulated photosensitised resin is totally dissolved in the developer. Development in machine needs a special developer (item code AR26).

After development, clean with water before etching.

ETCHING

In a tray use a ferric chloride at 36°B, in a foam machine, use a ferric chloride at 41°B. In a spraying machine, use a boosted ferric chloride (cleaner and more constant etching time).

STRIPPING

CIF resin is thermoweldable; it can be let on the board even during cutting and drilling operations. To get it off, use the CIF stripper or a stamp full of alcohol.

TABLE OF PROBLEMS AND THEIR SOLUTIONS

Phosotsensitised circuits. Development can not be done.

Cut circuit during development or blur development

Holes in copper after etching

No etching

Thin pads, reduced after etching

CAUSES

Too short time exposure. Too low development T°. Saturated developer

Bad contact of the original upon the board. Too thick mylar. Drawing is not black enough.

Cuts on the drawing.

Overinsulated board. Drawing not opaque enough. Bad contact. Too long etching time.

Resin remains on the board. Saturated etching agent.

Les UV passent sur l'original. Phénomène de sous gravure. Mylar trop épais.

SOLUTIONS

Make tests with a grey scale (CIF test film) and a new developer. Mini T° 18°C

Better the pressure or verify the machine. Make a contact film (CIF reprophane film). Control the light box.

Verify the original and make tests with grey scale (CIF test

Increase exposure and development times Change the etching agent. Better the contact and the etching system. Make a contact

Upside down transfers.

ACCEPTABLE INTENSITY IN A PRINTED CIRCUIT TRACK:

Thickness of copper: 35 microns for a temperature difference (DT°) of 20°C.

Conductor width in mm	0,4	0,72	1,14	1,8	2,5	3,5	4,5	5,0	7,1
Acceptable intensity in A	1,3	2,7	3,8	5,2	6,8	8,3	9,7	11,2	13,0

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